

# XPedite7332

**End of Life**

Intel® Core™ i7 Processor-Based Conduction- or Air-Cooled 3U CompactPCI Module **Please contact X-ES Sales**

- ▶ Intel® Core™ i7-610E, -620LE, and -620UE processors
- ▶ Dual-core with Hyper-Threading Technology
- ▶ 3U CompactPCI module
- ▶ Conduction or air cooling
- ▶ Up to 8 GB of DDR3-1066 ECC SDRAM in two channels
- ▶ 32 MB NOR boot flash
- ▶ Up to 16 GB of NAND flash
- ▶ Configurable as system controller or peripheral
- ▶ Hosts an XMC
- ▶ Two 10/100/1000BASE-T Ethernet ports out J2
- ▶ Two RS-232/422/485 serial ports out J2
- ▶ Linux BSP
- ▶ Wind River VxWorks BSP
- ▶ QNX Neutrino BSP
- ▶ Green Hills INTEGRITY BSP
- ▶ Microsoft Windows drivers



## XPedite7332

The XPedite7332 is a conduction- or air-cooled 3U CompactPCI (cPCI) single board computer based on the Intel® Core™ i7 processor and Intel® QM57 chipset. With dual cores operating at 2.53, 2.0, or 1.06 GHz, the Intel® Core™ i7 delivers enhanced performance and efficiency for today's network information processing and other embedded computing applications.

Complementing processor performance, the XPedite7332 features up to 8 GB of DDR3-1066 ECC SDRAM in two channels, XMC support, and up to 16 GB of NAND flash. Two Gigabit Ethernet ports are routed to J2 for additional system flexibility.

The XPedite7332 provides a high-performance, feature-rich solution for current and future generations of embedded applications. Operating system support packages for the XPedite7332 include Wind River VxWorks, QNX Neutrino, Green Hills INTEGRITY, and Linux.

# X-ES

Extreme Engineering Solutions

*...Always Fast*

### Extreme Engineering Solutions

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**Processor**

- Intel® Core™ i7 processor operating at 2.53, 2.0, or 1.06 GHz
- Dual-core with Hyper-Threading Technology
- Intel® QM57 chipset
- Dual channel integrated memory controller
- Integrated graphics controller
- 4 MB of shared cache

**Memory**

- Up to 8 GB of DDR3-1066 ECC SDRAM in two channels
- 32 MB NOR boot flash
- Up to 16 GB of NAND flash

**J1 cPCI Interface**

- 32-bit PCI interface operating at 33 or 66 MHz
- System controller capable with onboard clocking and arbitration
- Peripheral slot capable

**J2 cPCI Interface**

- Two 10/100/1000BASE-T Ethernet ports
- Two RS-232/422/485 serial ports
- Four GPIO signals
- Four SATA ports
- Two USB 2.0 ports
- One DVI port

**XMC Site**

There are restrictions on the XMC front panel. Contact factory for details.

- x8 PCIe interface
- Two SATA ports

**Software Support**

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers

**Physical Characteristics**

- Conduction- or air-cooled 3U CompactPCI form factor
- Dimensions: 100 mm x 160 mm

**Environmental Requirements**

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

**Power Requirements**

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.04 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz	0.1 g <sup>2</sup> /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

